

**HEXFET® POWER MOSFET  
 THRU-HOLE (TO-257AA)**

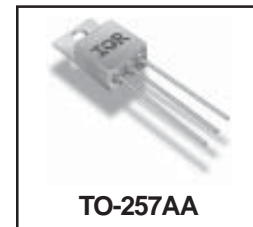
**IRL7Y1905C  
 50V, N-CHANNEL**

**Product Summary**

Part Number	BV <sub>DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub>
IRL7Y1905C	50V	0.125Ω	10A

Seventh Generation HEXFET® power MOSFETs from International Rectifier utilize advanced processing techniques to achieve the lowest possible on-resistance per silicon unit area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient device for use in a wide variety of applications.

These devices are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high-energy pulse circuits.



**TO-257AA**

**Features:**

- Low R<sub>DS(on)</sub>
- Avalanche Energy Ratings
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Light Weight

**Absolute Maximum Ratings**

	Parameter		Units
I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 25°C	Continuous Drain Current	10	A
I <sub>D</sub> @ V <sub>GS</sub> = 10V, T <sub>C</sub> = 100°C	Continuous Drain Current	5.0	
I <sub>DM</sub>	Pulsed Drain Current ①	20	
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Max. Power Dissipation	15	W
	Linear Derating Factor	0.12	W/°C
V <sub>GS</sub>	Gate-to-Source Voltage	± 16	V
EAS	Single Pulse Avalanche Energy ②	20	mJ
I <sub>AR</sub>	Avalanche Current ①	10	A
E <sub>AR</sub>	Repetitive Avalanche Energy ①	7.5	mJ
dv/dt	Peak Diode Recovery dv/dt ③	2.2	V/ns
T <sub>J</sub>	Operating Junction	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range		
	Lead Temperature	300 (0.063in./1.6mm from case for 10sec)	
	Weight	4.3 (Typical)	g

For footnotes refer to the last page

**Electrical Characteristics @ T<sub>j</sub> = 25°C (Unless Otherwise Specified)**

	Parameter	Min	Typ	Max	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	50	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	—	0.058	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1.0mA
R <sub>DSON</sub>	Static Drain-to-Source On-State Resistance	—	—	0.125	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	1.0	—	2.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
g <sub>fs</sub>	Forward Transconductance	1.1	—	—	S (r <sub>θ</sub> )	V <sub>DS</sub> = 1.0V, I <sub>DS</sub> = 200mA ④
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	—	—	10	μA	V <sub>DS</sub> = 2.5V, V <sub>GS</sub> = 0V
		—	—	25		V <sub>DS</sub> = 2.5V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 60°C
I <sub>GSS</sub>	Gate-to-Source Leakage Forward	—	—	100	nA	V <sub>GS</sub> = 2.5V
I <sub>GSS</sub>	Gate-to-Source Leakage Reverse	—	—	-100		V <sub>GS</sub> = -2.5V
Q <sub>g</sub>	Total Gate Charge	—	—	13	nC	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A V <sub>DS</sub> = 44V
Q <sub>gs</sub>	Gate-to-Source Charge	—	—	2.0		
Q <sub>gd</sub>	Gate-to-Drain ('Miller') Charge	—	—	3.0		
t <sub>d(on)</sub>	Turn-On Delay Time	—	—	8.0	ns	V <sub>DD</sub> = 27.5V, I <sub>D</sub> = 10A, V <sub>GS</sub> = 5.0V, R <sub>G</sub> = 12Ω
t <sub>r</sub>	Rise Time	—	—	96		
t <sub>d(off)</sub>	Turn-Off Delay Time	—	—	23		
t <sub>f</sub>	Fall Time	—	—	67		
L <sub>S</sub> + L <sub>D</sub>	Total Inductance	—	6.8	—	nH	Measured from drain lead (6mm/ 0.25in. from package) to source lead (6mm/0.25in. from package)
C <sub>iss</sub>	Input Capacitance	—	230	350	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	70	—		
C <sub>rss</sub>	Reverse Transfer Capacitance	—	8.0	—		

**Source-Drain Diode Ratings and Characteristics**

	Parameter	Min	Typ	Max	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	10	A	
I <sub>SM</sub>	Pulse Source Current (Body Diode) ①	—	—	20		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.3	V	T <sub>j</sub> = 25°C, I <sub>S</sub> = 10A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	Reverse Recovery Time	—	—	64	ns	T <sub>j</sub> = 25°C, I <sub>F</sub> = 10A, di/dt ≤ 100A/μs
Q <sub>RR</sub>	Reverse Recovery Charge	—	—	85	nC	V <sub>DD</sub> ≤ 30V ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> .				

**Thermal Resistance**

	Parameter	Min	Typ	Max	Units	Test Conditions
R <sub>thJC</sub>	Junction-to-Case	—	—	8.33	°C/W	

Note: Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

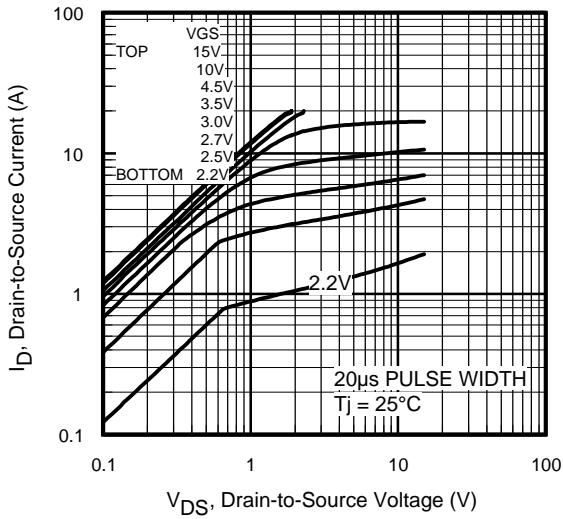


Fig 1. Typical Output Characteristics

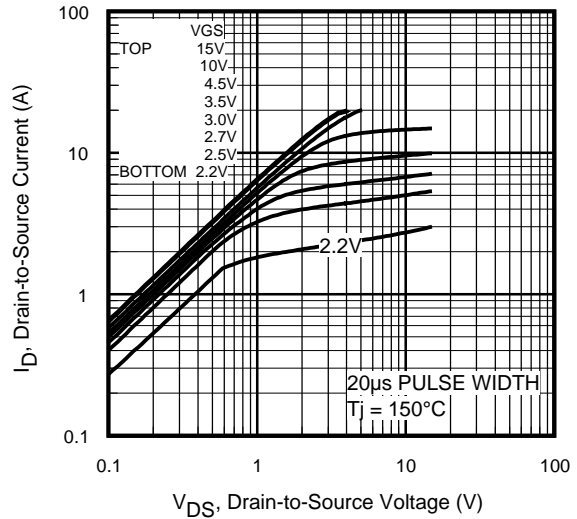


Fig 2. Typical Output Characteristics

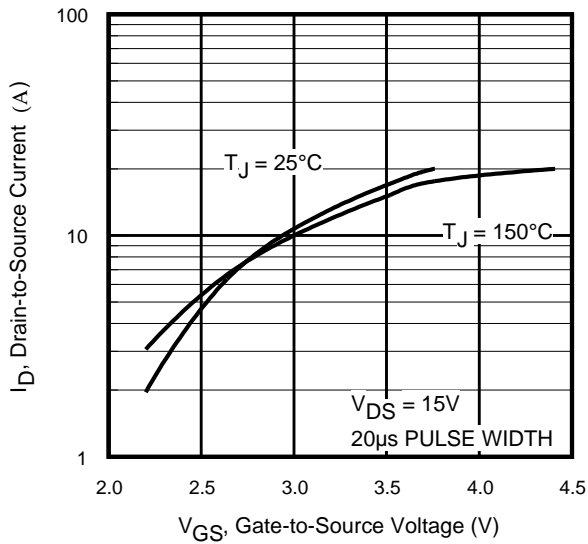


Fig 3. Typical Transfer Characteristics

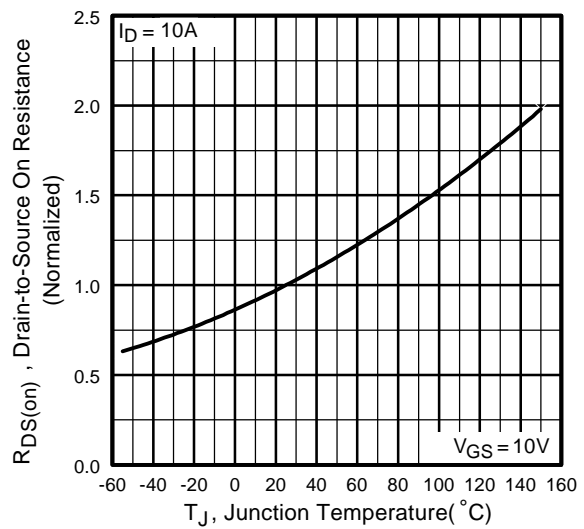
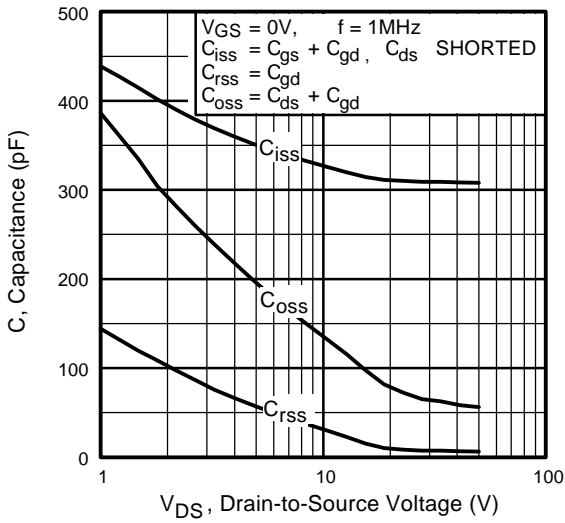
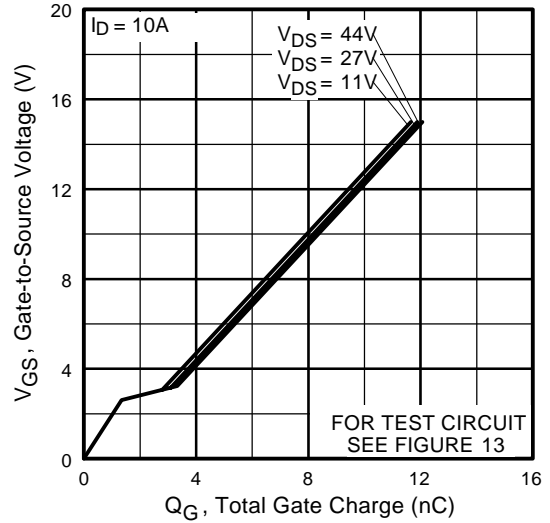


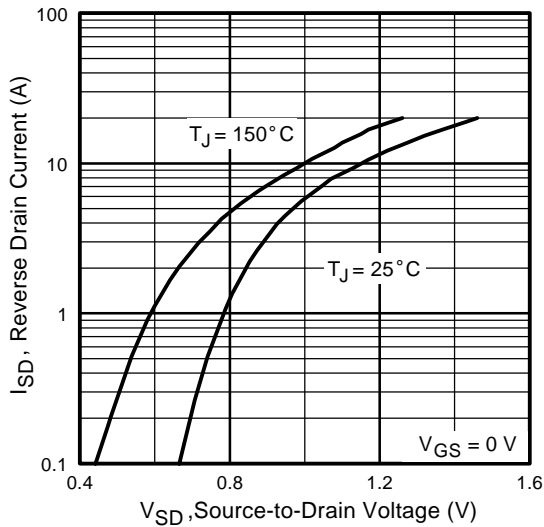
Fig 4. Normalized On-Resistance  
Vs. Temperature



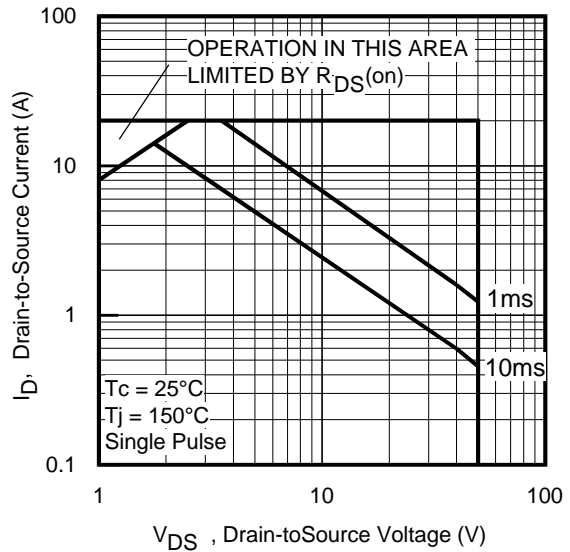
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



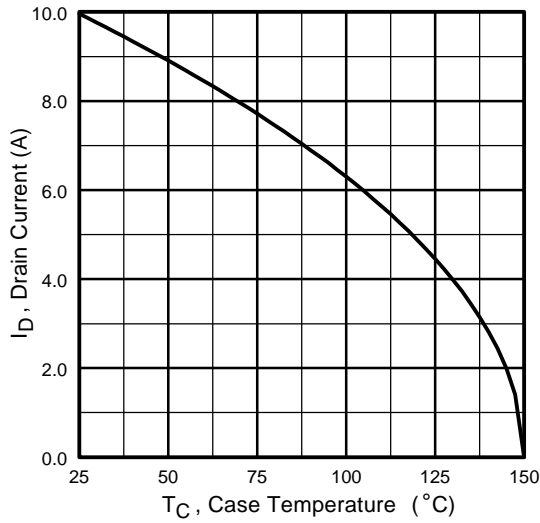
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



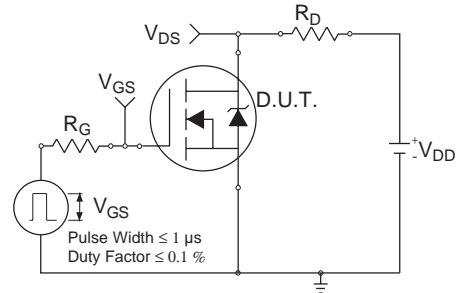
**Fig 7.** Typical Source-Drain Diode Forward Voltage



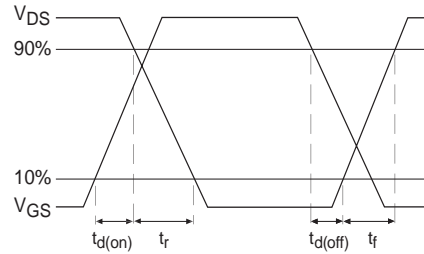
**Fig 8.** Maximum Safe Operating Area



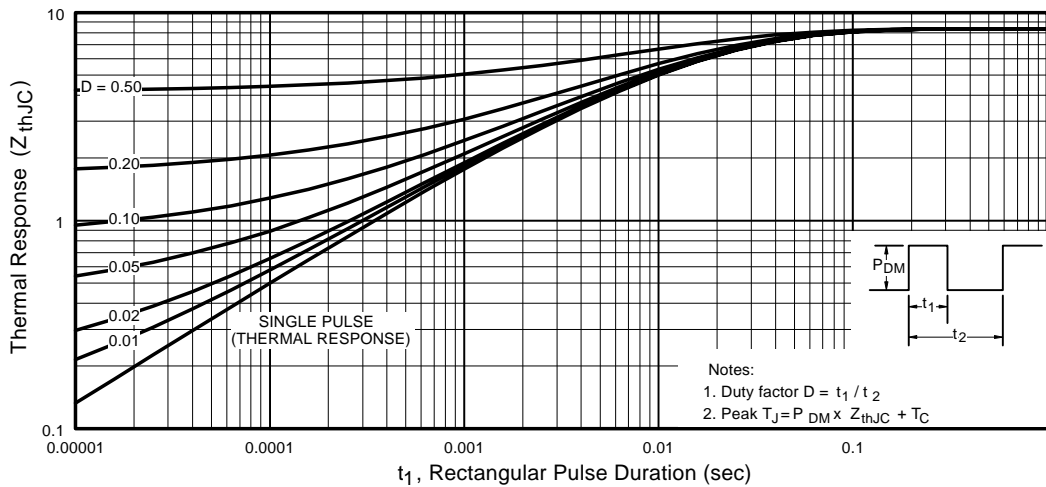
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



**Fig 10b.** Switching Time Waveforms



**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

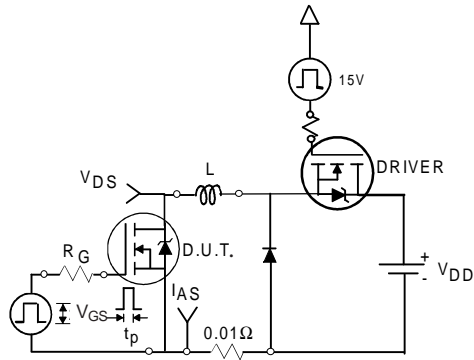


Fig 12a. Unclamped Inductive Test Circuit

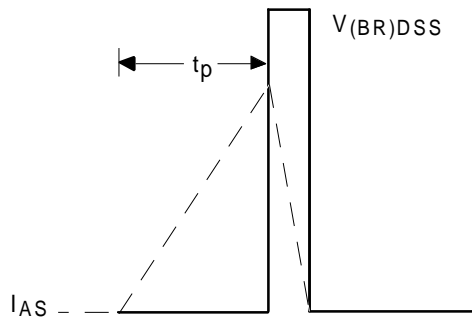


Fig 12b. Unclamped Inductive Waveforms

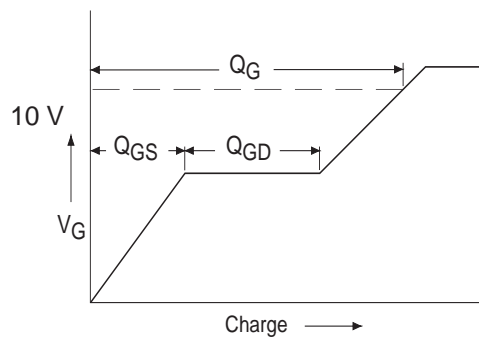


Fig 13a. Basic Gate Charge Waveform

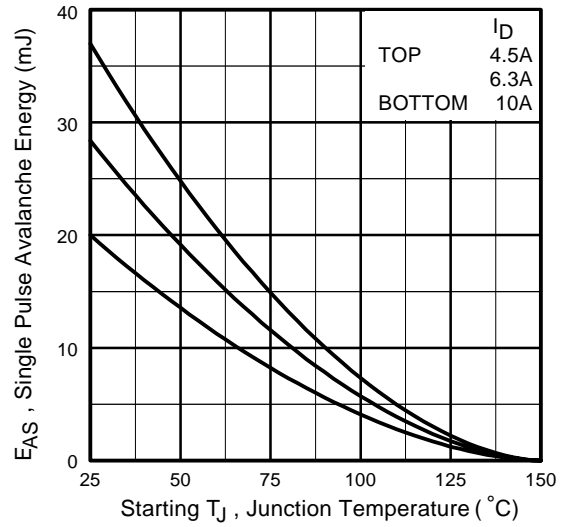


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

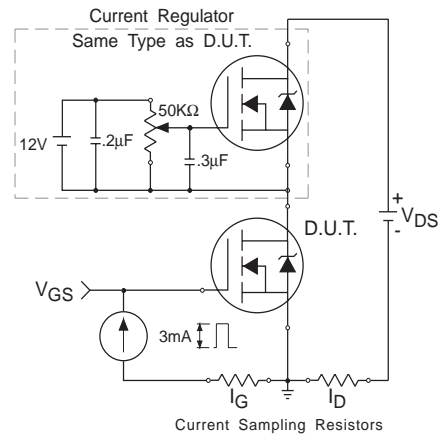


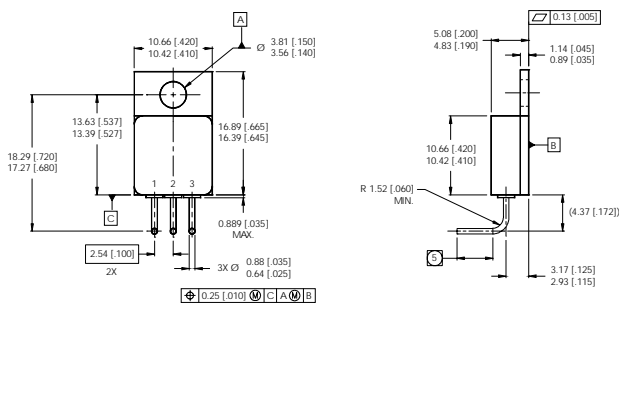
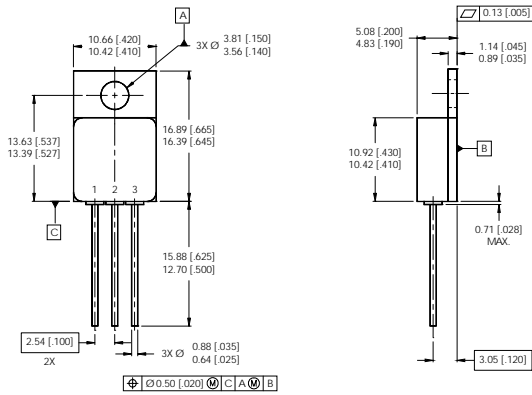
Fig 13b. Gate Charge Test Circuit

**Footnotes:**

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ②  $V_{DD} = 25\text{ V}$ , Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.4\text{mH}$   
Peak  $I_{AS} = 10\text{A}$ ,  $V_{GS} = 10\text{V}$ ,  $R_G = 25\Omega$
- ③  $I_{SD} \leq 10\text{A}$ ,  $di/dt \leq 230\text{ A}/\mu\text{s}$ ,  
 $V_{DD} \leq 50\text{V}$ ,  $T_J \leq 150^\circ\text{C}$
- ④ Pulse width  $\leq 300\ \mu\text{s}$ ; Duty Cycle  $\leq 2\%$

**Case Outline and Dimensions — TO-257AA**

Lead Formed Option



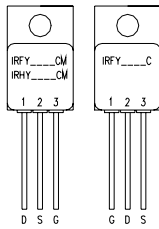
NOTES:

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-257AA

NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. THIS OUTLINE IS A MODIFIED TO-257AA JEDEC OUTLINE.
- ⑤ LEADS ARE SOLDER DIPPED TO THIS DIMENSION.
6. LEADS TO BE TRIMMED TO  $10.795 [0.425] \pm 0.635 [0.025]$  BEFORE LEADFORMING.

CERAMIC EYELETS



PIN ASSIGNMENTS

- 1 = GATE
- 2 = DRAIN
- 3 = SOURCE